

KBPC25005G(W) thru 2510G(W)

GLASS PASSIVATED BRIDGE RECTIFIERS

REVERSE VOLTAGE - 50 to 1000 Volts FORWARD CURRENT - 25 Amperes

FEATURES

- Rating to 1000V PRV
- High efficiency
- Glass passivated chip junction
- Electrically isolated metal case for maximum heat dissipation
- UL recognized file # E95060

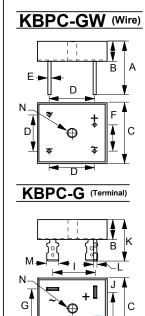
MECHANICAL DATA

• Case : Mounted in the bridge encapsulation

Mounting : Hole for # 10 screwPoarity : As marked on case

• Weight: 0.85 ounces, 24.0 grams (terminal)

: 0.74 ounces , 21.0 grams (wire)



KBPC-G/KBPC-GW						
DIM.	MIN. MAX.					
Α	31.80	-				
В	7.90	8.40				
С	28.30	28.80				
D	17.60	18.60				
Е	0.97	1.07				
F	10.90	11.90				
G	17.60	18.60				
Н	13.80	14.80				
I	16.10	17.10				
J	16.10	17.10				
K	18.80	21.30				
L	0.76	0.86				
M	6.30	6.50				
N	HOLE FOR NO. 10 SCREW					
	5.08	5.59				
All Dimensions in millimeter						

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

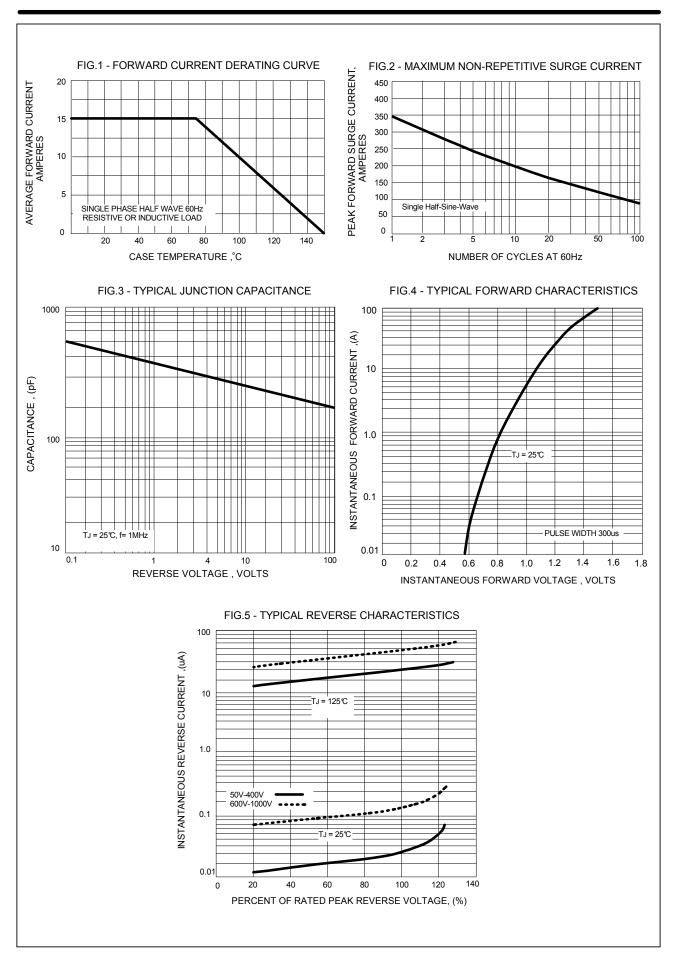
CHARACTERISTICS	SYMBOL	KBPC25 005G/W	KBPC25 01G/W	KBPC25 02G/W	KBPC25 04G/W	KBPC25 06G/W	KBPC25 08G/W	KBPC25 10G/W	UNIT
Maximum Recurrent Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current @Tc=Ta	l(AV)				25.0				Α
Peak Forward Surge Current 8.3ms single half sine-wave super imposed on rated load	IFSM	350						А	
Maximum forward Voltage at 12.5A DC	VF				1.1				V
Maximum DC Reverse Current at Rated DC Blocking Voltage @TJ =25℃ @TJ =125℃	lR	5.0 500						uA	
I²t Rating for fusing (t < 8.3ms), (Note 1)	I ² t				508				A ² S
Typical Junction Capacitance per element (Note 2)	Cı				300				pF
Typical Thermal Resistance (Note 3)	Rejc				3.0				°C/W
Operating Temperature Range	TJ			-:	55 to +150)			°C
Storage Temperature Range	Tstg			-	55 to +150)			°C

NOTES: 1.Measured at non-repetitive, for greater than 1ms and less than 8.3ms 2.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

3.Device mounted on 300mm x 300mm x 1.6mm Cu Plate Heatsink.

REV. 4, Sep-2010, KBDI02







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